

Pb Free Product

### Description

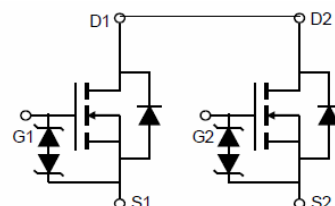
The RST8651Q uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### General Features

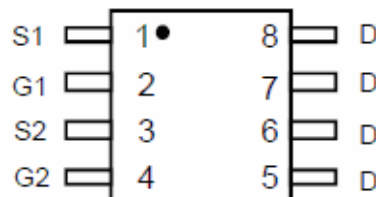
- $V_{DS} = 20V, I_D = 10A$   
 $R_{DS(ON)} < 11m\Omega @ V_{GS}=4.5V$   
 $R_{DS(ON)} < 11.5m\Omega @ V_{GS}=4V$   
 $R_{DS(ON)} < 12.5m\Omega @ V_{GS}=3.1V$   
 $R_{DS(ON)} < 15.5m\Omega @ V_{GS}=2.5V$
- High density cell design for ultra low  $R_{ds(on)}$
- Fully characterized avalanche voltage and current
- 2.5V Drive
- Common-drain type

### Application

- Battery protection switch
- Mobile device battery charging and discharging



Schematic diagram



Pin Assignment



DFN 3x3 top view

### Package Marking and Ordering Information

| Device Marking | Device   | Device Package | Reel Size | Tape width | Quantity |
|----------------|----------|----------------|-----------|------------|----------|
| RST8651Q       | RST8651Q | DFN 3x3        | -         | -          | -        |

### Absolute Maximum Ratings ( $T_C=25^{\circ}C$ unless otherwise noted)

| Parameter                                        | Symbol         | Limit      | Unit        |
|--------------------------------------------------|----------------|------------|-------------|
| Drain-Source Voltage                             | $V_{DS}$       | 20         | V           |
| Gate-Source Voltage                              | $V_{GS}$       | $\pm 12$   | V           |
| Drain Current-Continuous                         | $I_D$          | 10         | A           |
| Pulsed Drain Current                             | $I_{DM}$       | 32         | A           |
| Maximum Power Dissipation                        | $P_D$          | 1.5        | W           |
| Operating Junction and Storage Temperature Range | $T_J, T_{STG}$ | -55 To 150 | $^{\circ}C$ |

### Thermal Characteristic

|                                                             |                 |    |               |
|-------------------------------------------------------------|-----------------|----|---------------|
| Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup> | $R_{\theta JA}$ | 83 | $^{\circ}C/W$ |
|-------------------------------------------------------------|-----------------|----|---------------|

**Electrical Characteristics (TC=25°C unless otherwise noted)**

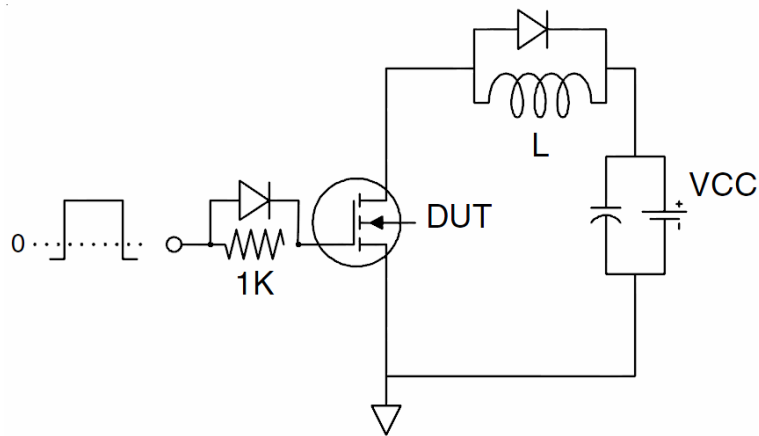
| Parameter                                     | Symbol              | Condition                                                                               | Min | Typ  | Max  | Unit |
|-----------------------------------------------|---------------------|-----------------------------------------------------------------------------------------|-----|------|------|------|
| Off Characteristics                           |                     |                                                                                         |     |      |      |      |
| Drain-Source Breakdown Voltage                | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250μA                                               | 20  |      | -    | V    |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>    | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V                                               | -   | -    | 1    | μA   |
| Gate-Body Leakage Current                     | I <sub>GSS</sub>    | V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V                                              | -   | -    | ±10  | μA   |
| On Characteristics <sup>(Note 3)</sup>        |                     |                                                                                         |     |      |      |      |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                | 0.5 | 0.7  | 1    | V    |
| Drain-Source On-State Resistance              | R <sub>DS(ON)</sub> | V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A                                              | -   | 7.2  | 11   | mΩ   |
|                                               |                     | V <sub>GS</sub> =4 V, I <sub>D</sub> =5A                                                | -   | 7.4  | 11.5 |      |
|                                               |                     | V <sub>GS</sub> =3.1V, I <sub>D</sub> =5A                                               |     | 7.8  | 12.5 |      |
|                                               |                     | V <sub>GS</sub> =2.5V, I <sub>D</sub> =2.5A                                             |     | 8.6  | 15.5 |      |
| Forward Transconductance                      | g <sub>FS</sub>     | V <sub>DS</sub> =10V, I <sub>D</sub> =5A                                                | 5   | -    | -    | S    |
| Dynamic Characteristics <sup>(Note4)</sup>    |                     |                                                                                         |     |      |      |      |
| Input Capacitance                             | C <sub>iss</sub>    | V <sub>DS</sub> =10V, V <sub>GS</sub> =0V,<br>F=1.0MHz                                  | -   | 1255 | -    | PF   |
| Output Capacitance                            | C <sub>oss</sub>    |                                                                                         | -   | 220  | -    | PF   |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>    |                                                                                         | -   | 168  | -    | PF   |
| Switching Characteristics <sup>(Note 4)</sup> |                     |                                                                                         |     |      |      |      |
| Turn-on Delay Time                            | t <sub>d(on)</sub>  | V <sub>DD</sub> =10V, I <sub>D</sub> =5A<br>V <sub>GS</sub> =10V, R <sub>GEN</sub> =50Ω | -   | 300  | -    | nS   |
| Turn-on Rise Time                             | t <sub>r</sub>      |                                                                                         | -   | 1000 | -    | nS   |
| Turn-Off Delay Time                           | t <sub>d(off)</sub> |                                                                                         | -   | 4000 | -    | nS   |
| Turn-Off Fall Time                            | t <sub>f</sub>      |                                                                                         | -   | 2500 | -    | nS   |
| Total Gate Charge                             | Q <sub>g</sub>      | V <sub>DS</sub> =10V, I <sub>D</sub> =10A,<br>V <sub>GS</sub> =10V                      | -   | 29   | -    | nC   |
| Gate-Source Charge                            | Q <sub>gs</sub>     |                                                                                         | -   | 5.2  | -    | nC   |
| Gate-Drain Charge                             | Q <sub>gd</sub>     |                                                                                         | -   | 6.3  | -    | nC   |
| Drain-Source Diode Characteristics            |                     |                                                                                         |     |      |      |      |
| Diode Forward Voltage <sup>(Note 3)</sup>     | V <sub>SD</sub>     | V <sub>GS</sub> =0V, I <sub>S</sub> =10A                                                | -   | 0.85 | 1.2  | V    |
| Diode Forward Current <sup>(Note 2)</sup>     | I <sub>S</sub>      |                                                                                         | -   | -    | 10   | A    |

**Notes:**

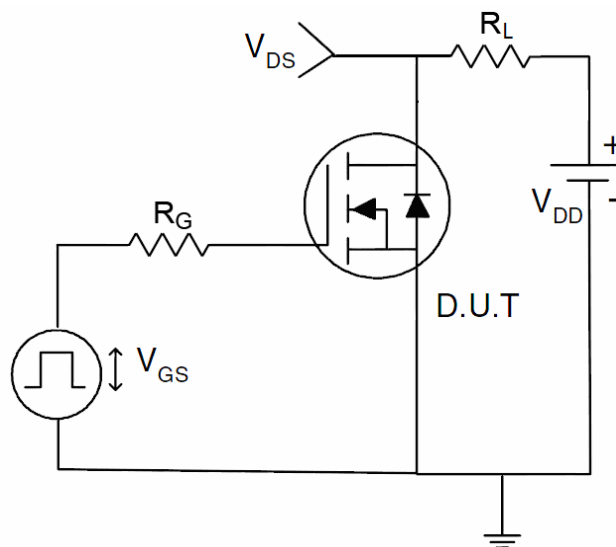
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

### Test Circuit

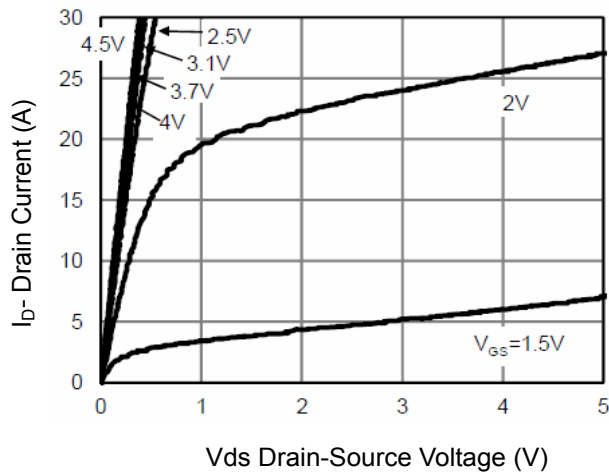
#### 1) Gate Charge Test Circuit



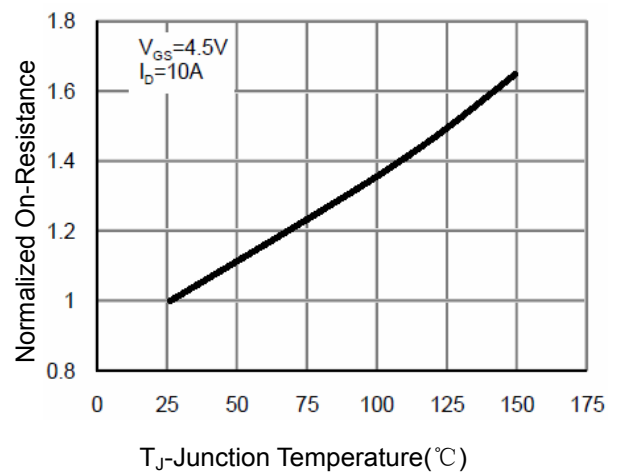
#### 2) Switch Time Test Circuit



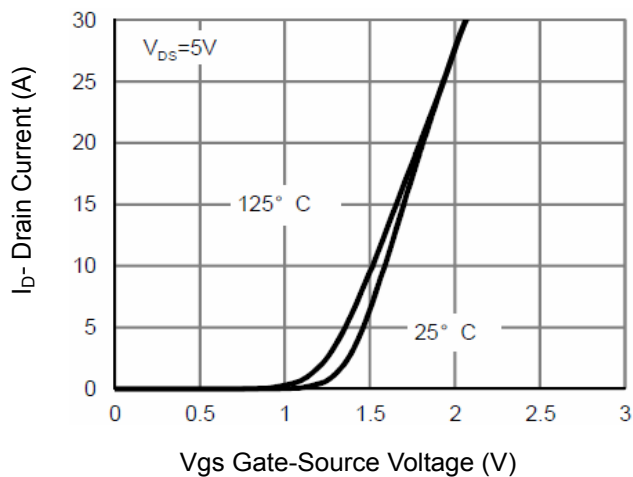
### Typical Electrical and Thermal Characteristics (Curves)



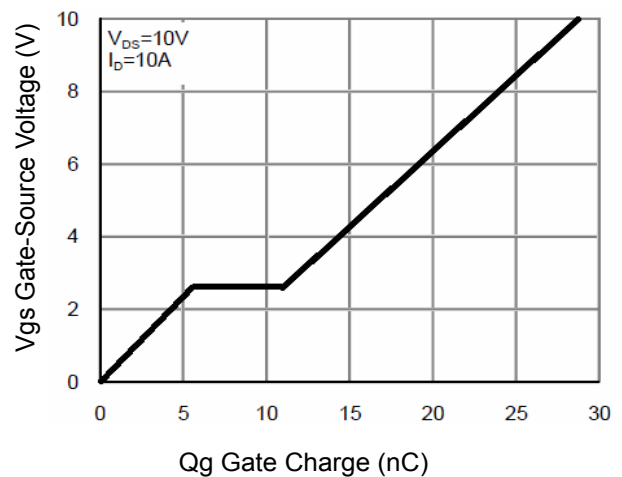
**Figure 1 Output Characteristics**



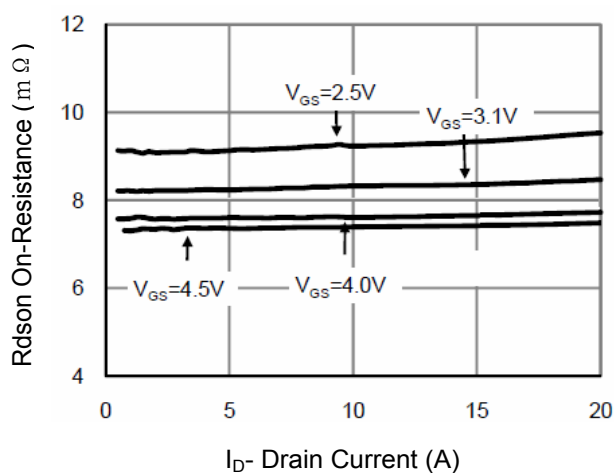
**Figure 4 Rdson-Junction Temperature**



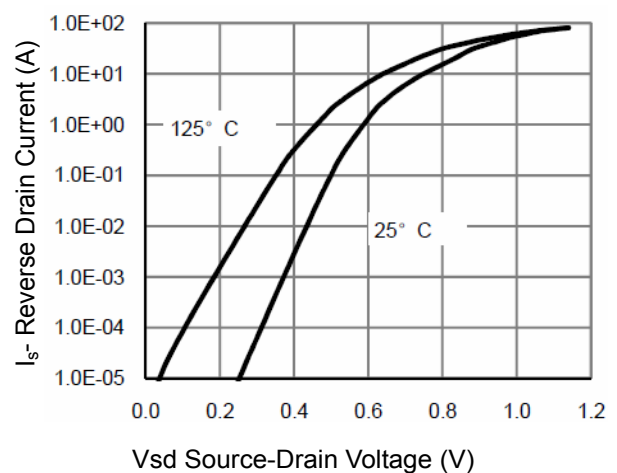
**Figure 2 Transfer Characteristics**



**Figure 5 Gate Charge**



**Figure 3 Rdson- Drain Current**



**Figure 6 Source- Drain Diode Forward**

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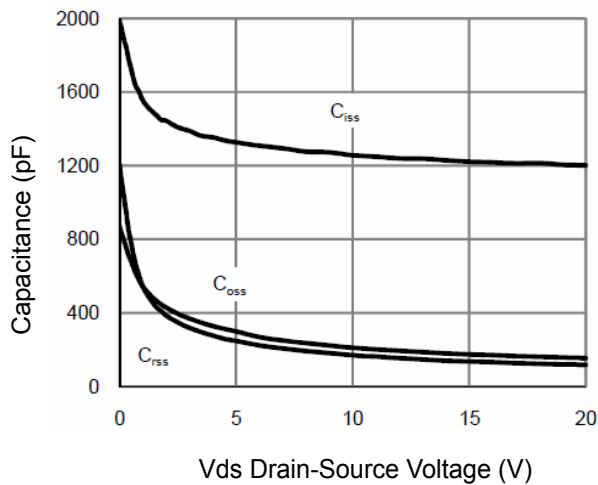


Figure 7 Capacitance vs Vds

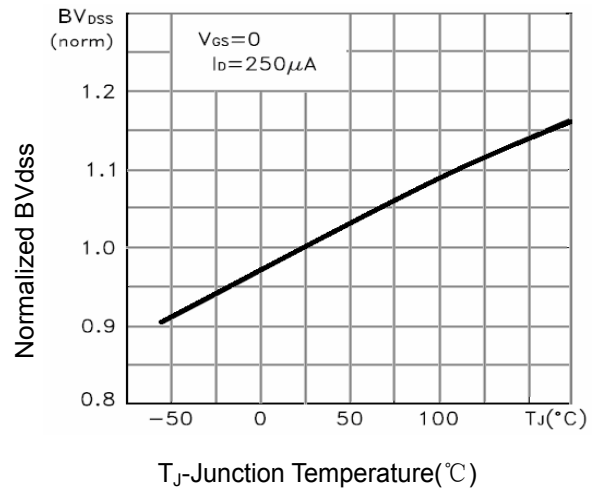


Figure 9  $BV_{DSS}$  vs Junction Temperature

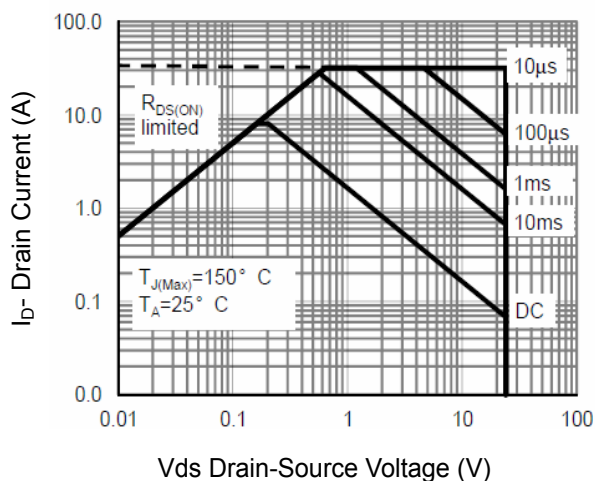


Figure 8 Safe Operation Area

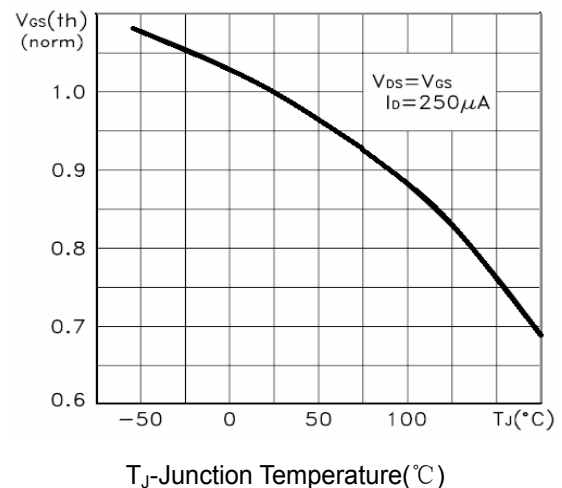


Figure 10  $V_{GS(th)}$  vs Junction Temperature

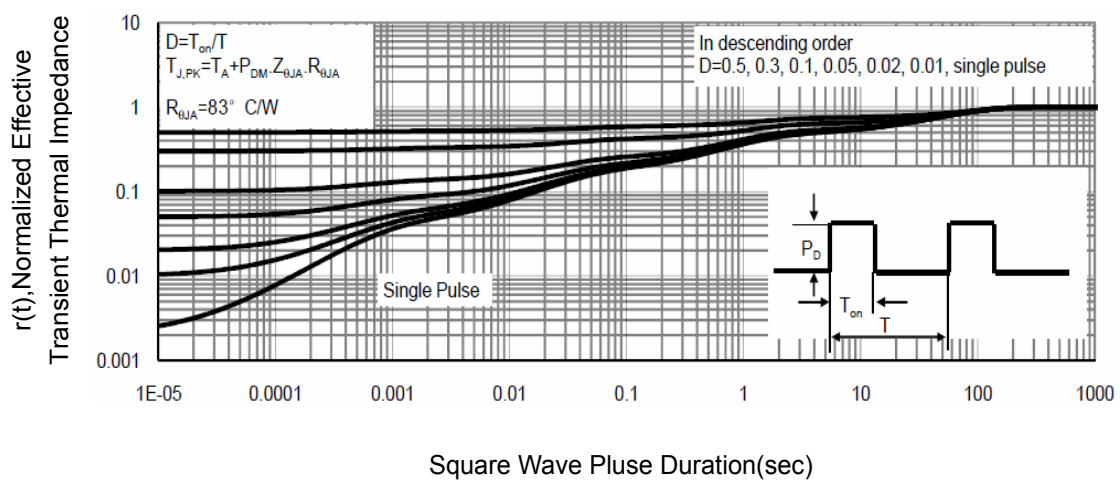
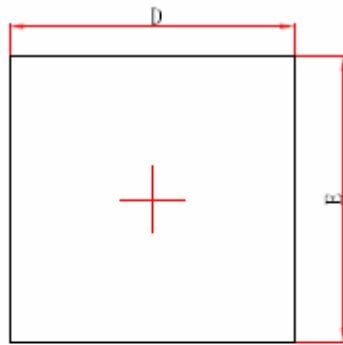
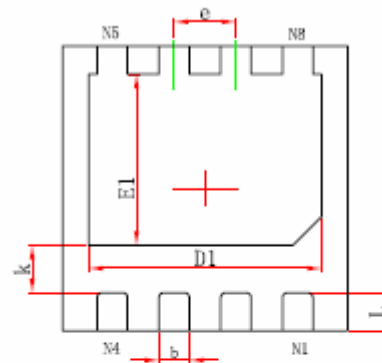


Figure 11 Normalized Maximum Transient Thermal Impedance

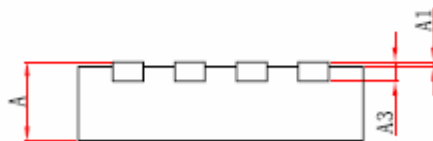
### DFN3X3 EP Package Information



Top View



Bottom View



Side View

| Symbol | Dimensions In Millimeters |             | Dimensions In Inches |             |
|--------|---------------------------|-------------|----------------------|-------------|
|        | Min.                      | Max.        | Min.                 | Max.        |
| A      | 0.700/0.800               | 0.800/0.900 | 0.028/0.031          | 0.031/0.035 |
| A1     | 0.000                     | 0.050       | 0.000                | 0.002       |
| A3     | 0.203REF.                 |             | 0.008REF.            |             |
| D      | 2.924                     | 3.076       | 0.115                | 0.121       |
| E      | 2.924                     | 3.076       | 0.115                | 0.121       |
| D1     | 2.350                     | 2.550       | 0.093                | 0.100       |
| E1     | 1.700                     | 1.900       | 0.067                | 0.075       |
| k      | 0.450                     | 0.550       | 0.018                | 0.022       |
| b      | 0.270                     | 0.370       | 0.011                | 0.015       |
| e      | 0.650TYP.                 |             | 0.026TYP.            |             |
| L      | 0.324                     | 0.476       | 0.013                | 0.019       |